

Part Number: KPTD-3216MGCK

MEGA GREEN

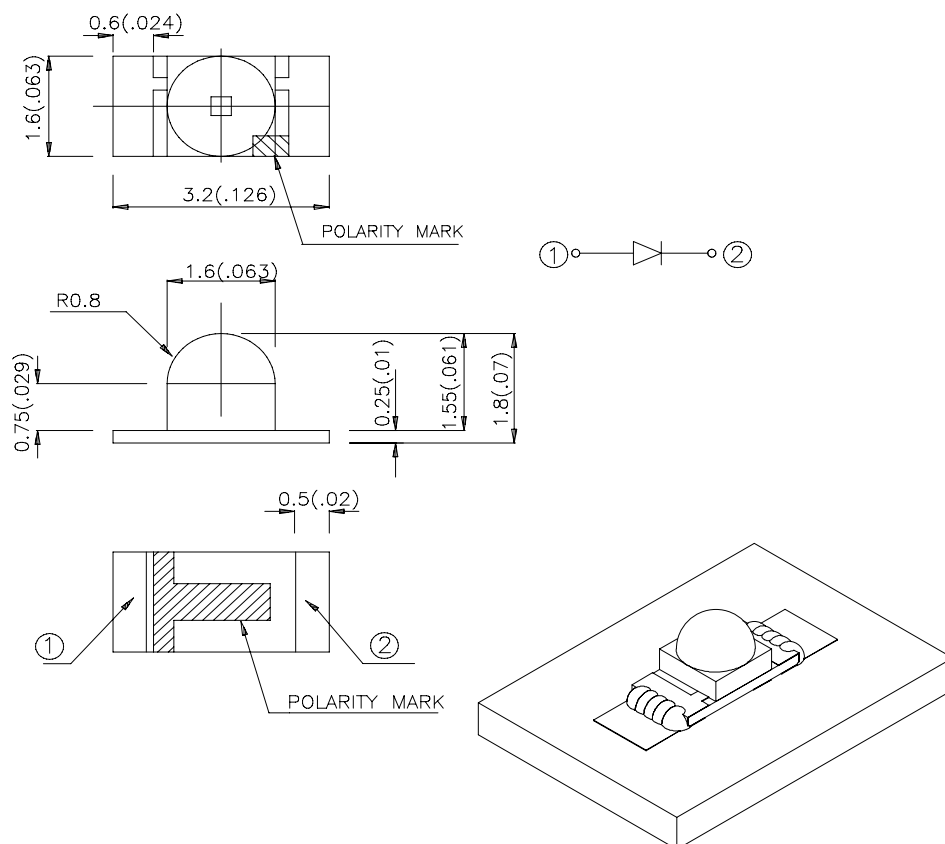
Features

- 3.2mmx1.6mm SMT LED, 1.8mm THICKNESS.
- LOW POWER CONSUMPTION.
- WIDE VIEWING ANGLE.
- IDEAL FOR BACKLIGHT AND INDICATOR.
- VARIOUS COLORS AND LENS TYPES AVAILABLE.
- PACKAGE: 2000PCS / REEL.
- MOISTURE SENSITIVITY LEVEL : LEVEL 3.
- RoHS COMPLIANT.

Description

The Mega Green source color devices are made with DH InGaAlP on GaAs substrate Light Emitting Diode.

Package Dimensions



Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is ± 0.2 (0.0079") unless otherwise noted.
3. Specifications are subject to change without notice.
4. The device has a single mounting surface. The device must be mounted according to the specifications.



Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Typ.	2θ1/2
KPTD-3216MGCK	MEGA GREEN (InGaAlP)	WATER CLEAR	110	250	50°

Notes:

1. $\theta_{1/2}$ is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.
2. Luminous intensity/ luminous flux: +/-15%.

Electrical / Optical Characteristics at T_A=25°C

Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λ_{peak}	Peak Wavelength	Mega Green	574		nm	I _F =20mA
$\lambda_D[1]$	Dominant Wavelength	Mega Green	570		nm	I _F =20mA
$\Delta\lambda_{1/2}$	Spectral Line Half-width	Mega Green	20		nm	I _F =20mA
C	Capacitance	Mega Green	15		pF	V _F =0V;f=1MHz
V _F [2]	Forward Voltage	Mega Green	2.1	2.5	V	I _F =20mA
I _R	Reverse Current	Mega Green		10	uA	V _R = 5V

Notes:

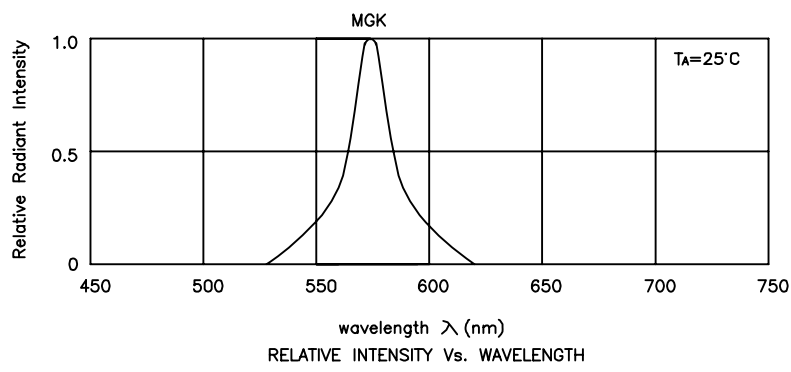
1. Wavelength: +/-1nm.
2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at T_A=25°C

Parameter	Mega Green	Units
Power dissipation	75	mW
DC Forward Current	30	mA
Peak Forward Current [1]	150	mA
Reverse Voltage	5	V
Operating/Storage Temperature	-40°C To +85°C	

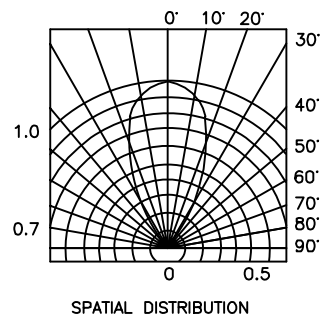
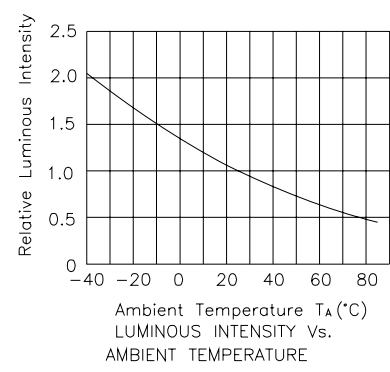
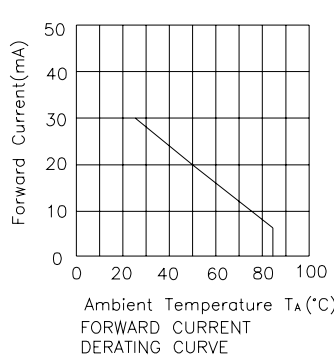
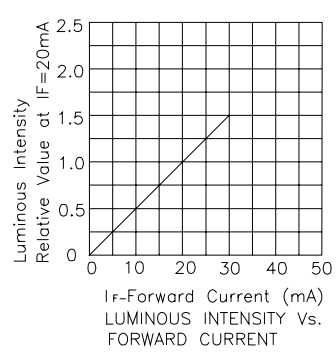
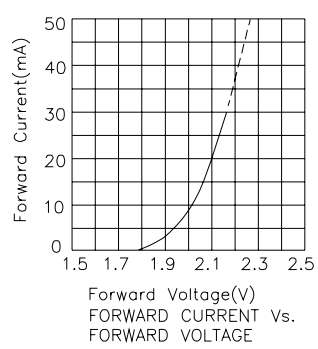
Note:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.



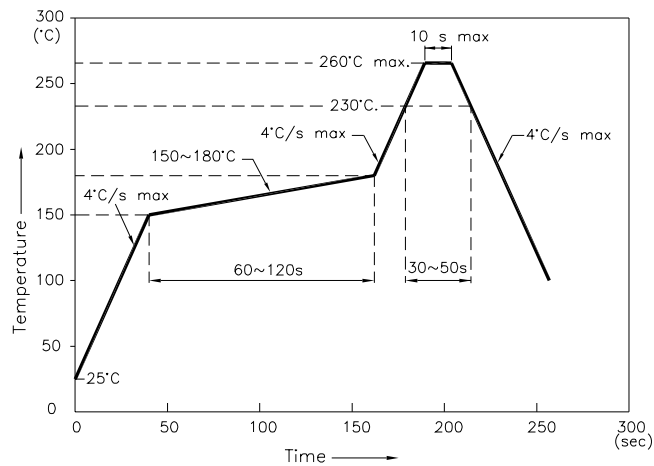
Mega Green

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Reflow Soldering Profile For Lead-free SMT Process.

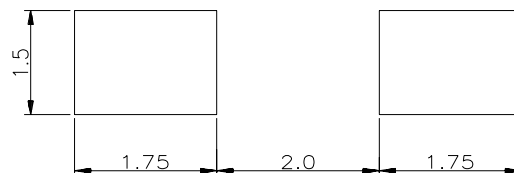


NOTES:

1. We recommend the reflow temperature $245^{\circ}\text{C} (+/-5^{\circ}\text{C})$. The maximum soldering temperature should be limited to 260°C .
2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

Recommended Soldering Pattern

(Units : mm; Tolerance ± 0.1)



Tape Specifications

(Units : mm)

